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Vishay Semiconductors

High Speed Infrared Emitting Diodes, 940 nm, GaAlAs, MQW



DESCRIPTION

VSMB294008 series are infrared, 940 nm emitting diodes in GaAlAs multi quantum well (MQW) technology with high radiant power and high speed, molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

APPLICATIONS

- Data transmission
- Miniature light barrier
- Photointerrupters
- · Optical switch
- · Control and drive circuits
- · Shaft encoders



FEATURES

- Package type: surface mount
- · Package form: GW, RGW
- Dimensions (L x W x H in mm): 2.3 x 2.3 x 2.8
- Peak wavelength: $\lambda_p = 940 \text{ nm}$
- High reliability
- · High radiant power
- · High radiant intensity
- Angle of half intensity: $\varphi = \pm 7^{\circ}$
- · Low forward voltage
- Suitable for high pulse current operation
- · Terminal configurations: gullwing or reserve gullwing
- Package matches with detector VEMD2000X01 series
- Floor life: 4 weeks, MSL 2a, acc. J-STD-020
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

PRODUCT SUMMARY					
COMPONENT	l _e (mW/sr)	φ (deg)	λ _P (nm)	t _r (ns)	
VSMB294008RG	70	± 7	940	15	
VSMB294008G	70	± 7	940	15	

Note

Test conditions see table "Basic Characteristics"

ORDERING INFORMATION					
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM		
VSMB294008RG	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Reverse gullwing		
VSMB294008G	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Gullwing		

Note

MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)					
PARAMETER	TEST CONDITION SYMBOL		VALUE	UNIT	
Reverse voltage		V _R	5	V	
Forward current		I _F	100	mA	
Surge forward current	t _p = 100 μs	I _{FSM}	500	mA	
Power dissipation		Pv	160	mW	
Junction temperature		Тj	100	°C	
Operating temperature range		T _{amb}	-40 to +85	°C	
Storage temperature range		T _{stg}	-40 to +100	°C	
Soldering temperature	according to fig. 10, J-STD-020	T _{sd}	260	°C	
Thermal resistance junction/ambient	J-STD-051, leads 7 mm, soldered on PCB	R _{thJA}	250	K/W	

Rev. 1.1, 19-Nov-14

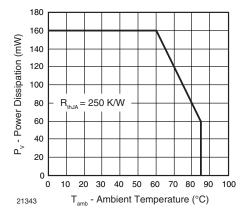
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Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

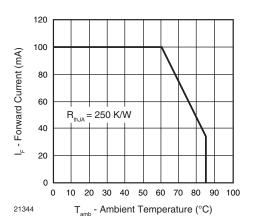
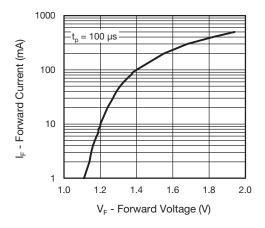


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I _F = 100 mA, t _p = 20 ms	V _F	1.15	1.45	1.75	V
	$I_F = 500 \text{ mA}, t_p = 100 \ \mu \text{s}$	V _F	-	1.8	-	V
Temperature coefficient of V_F	I _F = 100 mA	TK _{VF}	-	-0.64	-	mV/K
Reverse current	V _R = 5 V	I _R	-	-	10	μA
Junction capacitance	$V_{R} = 0 V, f = 1 MHz, E = 0 mW/cm^{2}$	CJ	-	38	-	pF
Radiant intensity	$I_F = 100 \text{ mA}, t_p = 100 \mu\text{s}$	l _e	30	70	115	mW/sr
	$I_F = 500 \text{ mA}, t_p = 100 \ \mu \text{s}$	l _e	-	260	-	mW/sr
Radiant power	$I_F = 100 \text{ mA}, t_p = 100 \mu\text{s}$	фе	-	40	-	mW
Temperature coefficient of radiant power	I _F = 100 mA	$TK\phi_{e}$	-	-0.43	-	%/K
Angle of half intensity		φ	-	± 7	-	deg
Peak wavelength	I _F = 30 mA	λ _p	920	940	960	nm
Spectral bandwidth	I _F = 30 mA	Δλ	-	25	-	nm
Temperature coefficient of λ_p	I _F = 30 mA	ΤΚλρ	-	0.25	-	nm/K
Rise time	$I_F = 100 \text{ mA}, 20 \% \text{ to } 80 \%$	t _r	-	15	-	ns
Fall time	$I_F = 100 \text{ mA}, 20 \% \text{ to } 80 \%$	t _f	-	15	-	ns
Cut-off frequency	$I_{DC} = 70 \text{ mA}, I_{AC} = 30 \text{ mA pp}$	f _c	-	23	-	MHz

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TYPICAL CHARACTERISTICS ($T_{amb} = 25 \text{ °C}$, unless otherwise specified)



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Fig. 3 - Forward Current vs. Forward Voltage

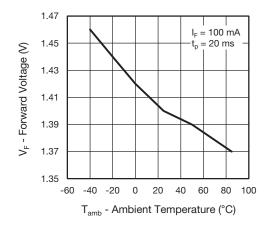


Fig. 4 - Forward Voltage vs. Ambient Temperature

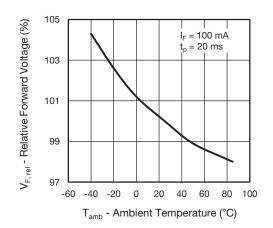


Fig. 5 - Relative Forward Voltage vs. Ambient Temperature

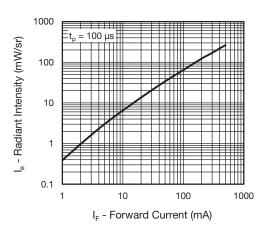


Fig. 6 - Radiant Intensity vs. Forward Current

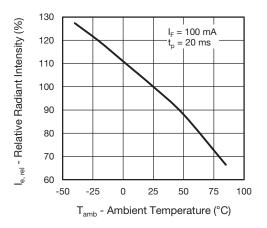


Fig. 7 - Radiant Intensity vs. Ambient Temperature

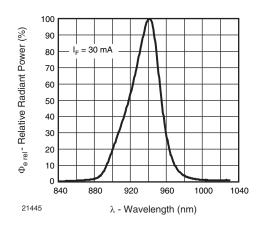


Fig. 8 - Relative Radiant Power vs. Wavelength

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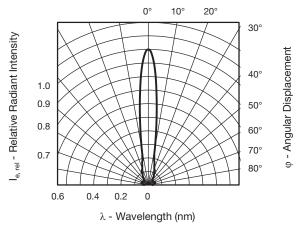


Fig. 9 - Relative Radiant Intensity vs. Angular Displacement

SOLDER PROFILE

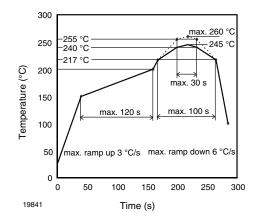


Fig. 10 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

VSMB294008RG, VSMB294008G

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DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

Conditions: T_{amb} < 30 °C, RH < 60 %

Moisture sensitivity level 2a, acc. to J-STD-020.

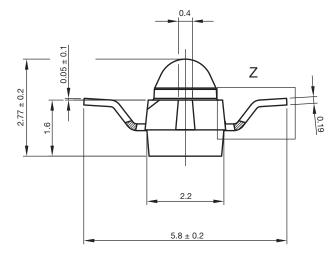
DRYING

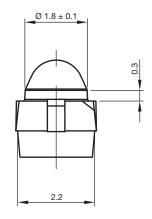
In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.



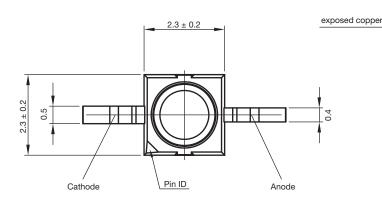
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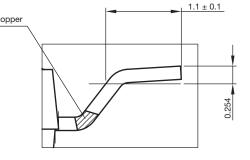
PACKAGE DIMENSIONS in millimeters: VSMB294008RG

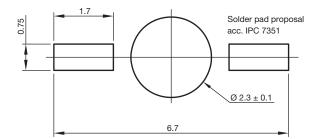




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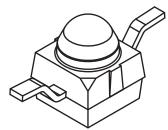




Drawing-No.: 6.544-5391.02-4 Issue: 2; 18.03.10 ²¹⁵¹⁷



Not indicated tolerances ± 0.1



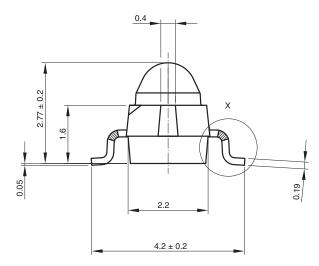
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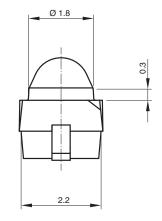
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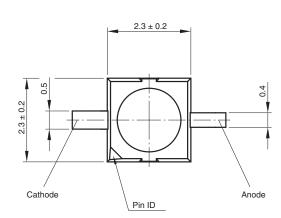


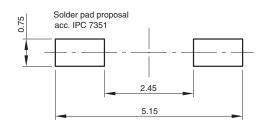
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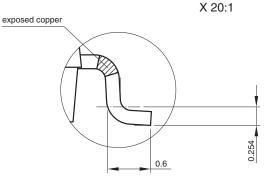






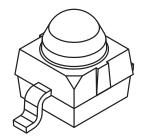


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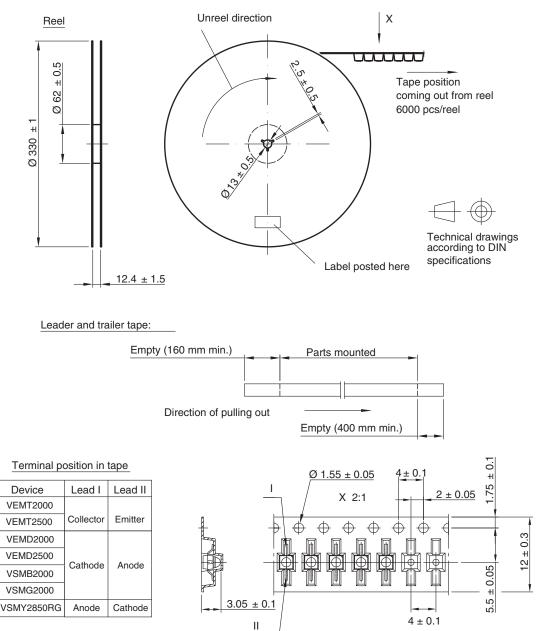
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TAPING AND REEL DIMENSIONS in millimeters: VSMB294008RG

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Drawing-No.: 9.800-5100.01-4 Issue: 2; 18.03.10 21572

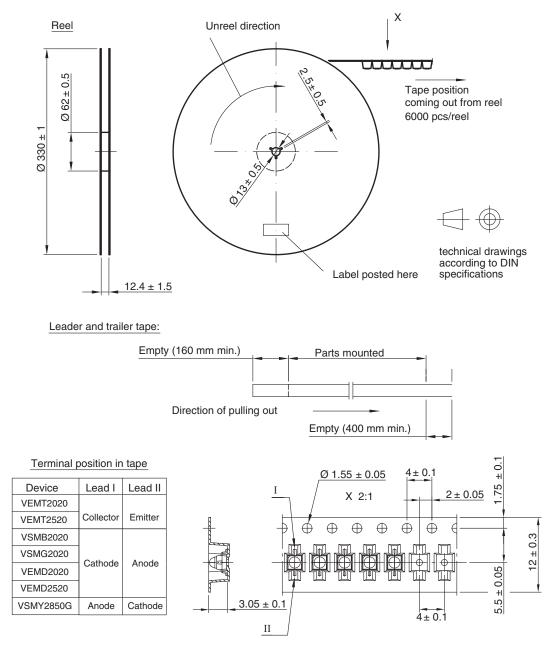
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TAPING AND REEL DIMENSIONS in millimeters: VSMB294008G



Drawing-No.: 9.800-5091.01-4 Issue: 3; 18.03.10 21571



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